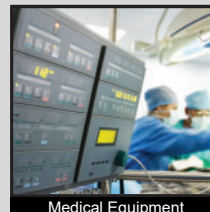
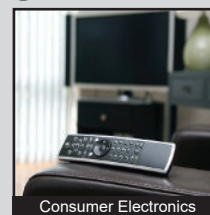
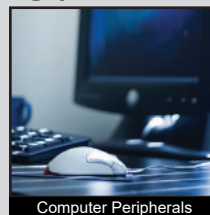
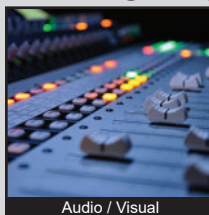


TL3275 SERIES TACT SWITCH

ANTI-VANDAL SWITCHES
 DETECTOR SWITCHES
 DIP SWITCHES
 KEYLOCK SWITCHES
 NAVIGATION SWITCHES
 PUSHBUTTON SWITCHES
 ROCKER SWITCHES
 ROTARY SWITCHES
 SLIDE SWITCHES
 SNAP ACTION SWITCHES
TACTILE SWITCHES
 TOGGLE SWITCHES
 CAP OPTIONS



APPLICATIONS / MARKETS



RoHS

SPECIFICATIONS

Electrical Rating: 50mA, 12VDC
Contact Resistance: 500mΩ Max. (Initial)
Insulation Resistance: 100MΩ Min. at 100VDC
Dielectric Strength: 250VAC for 1 Minute
Operating Temperature: -40°C to 85°C
Operating Force: 160gf ± 50gf
Operating Life: 100,000 cycles
Travel: 0.20mm ± 0.10mm
Function: SPST, Off-(On)
Bounce: 10msec Max.
Contact Material: Silver or Gold
Packaging: Tape and Reel, 1,400 pcs/reel

FEATURES & BENEFITS

- Right angle surface mount design
- Multiple LED options including dual LED
- Up to 100,000 cycle life expectancy
- Tape and Reel packaging
- Silver or Gold contact material

PART NUMBER CONFIGURATOR

Series	Actuator	Operating Force	LED Option	Contact Material
<input type="text" value="TL3275"/>	<input type="text" value="A - 3.90"/>	<input type="text" value="F160 - 160 gf"/>	<input type="text" value="N"/>	<input type="text" value="Q"/>
			N - No LED B - Blue G - Green R - Red Y - Yellow W - White BG - Blue/Green Bi-color BR - Blue/Red Bi-color BY - Blue/Yellow Bi-color BW - Blue/White Bi-color GR - Green/Red Bi-color GY - Green/Yellow Bi-color GW - Green/White Bi-color RY - Red/Yellow Bi-color RW - Red/White Bi-color YW - Yellow/White Bi-color	Q - Silver R - Gold

Specifications subject to change without notice 12.6.2022



E-SWITCH®

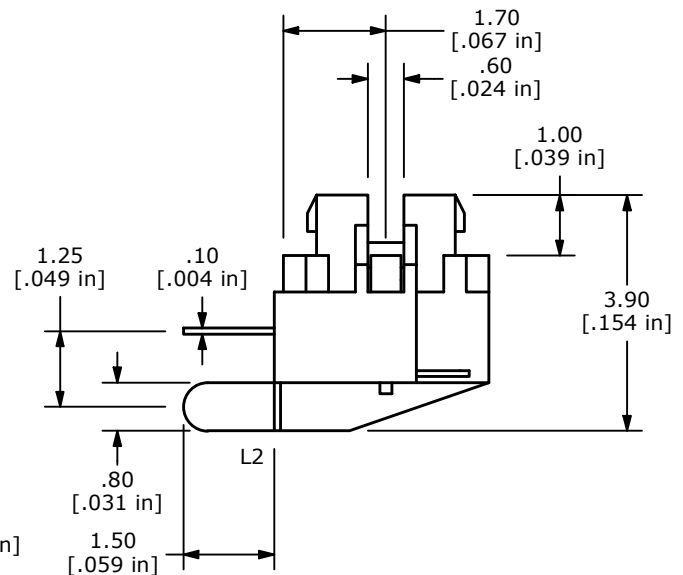
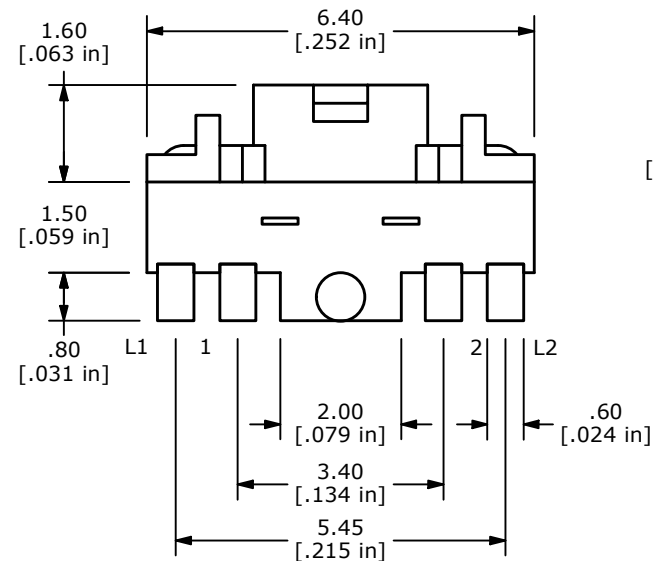
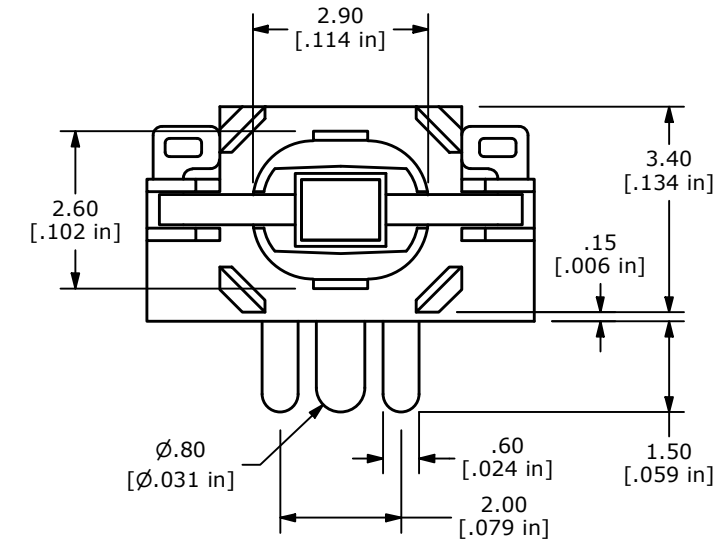
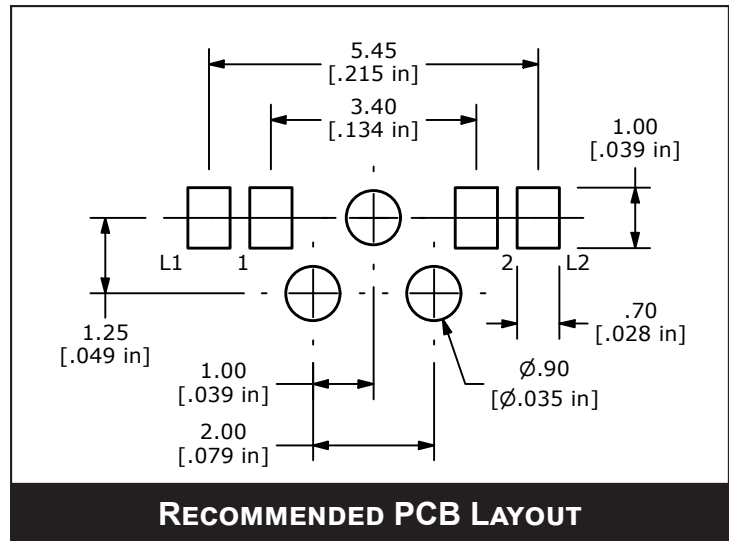
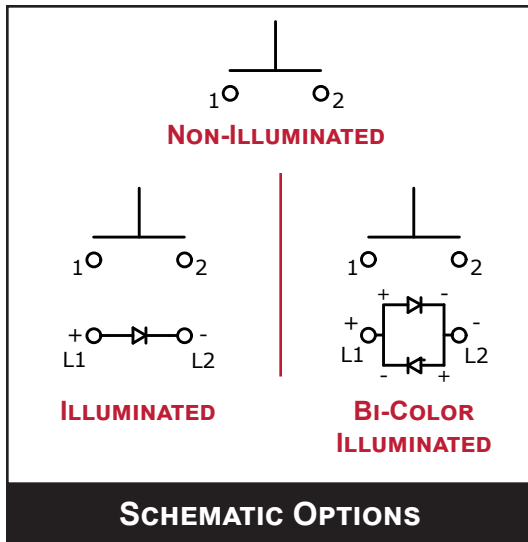
www.e-switch.com

800.867.2717

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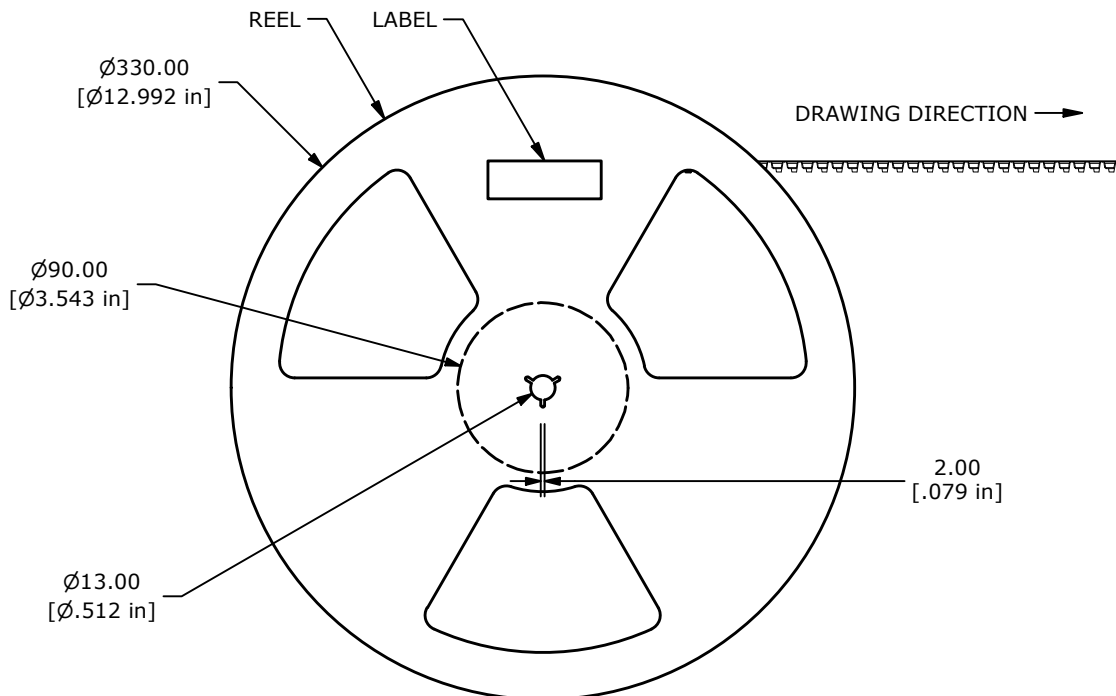
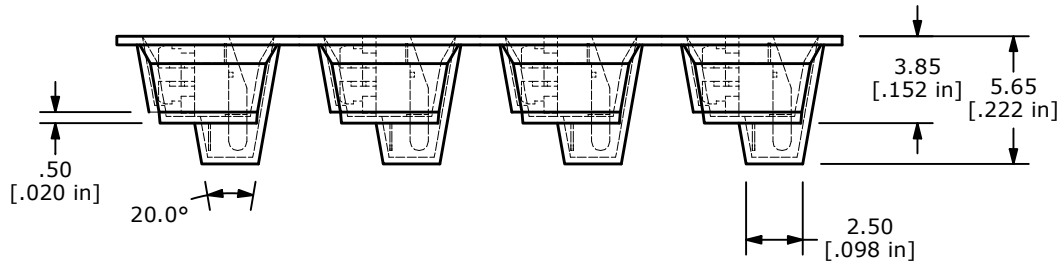
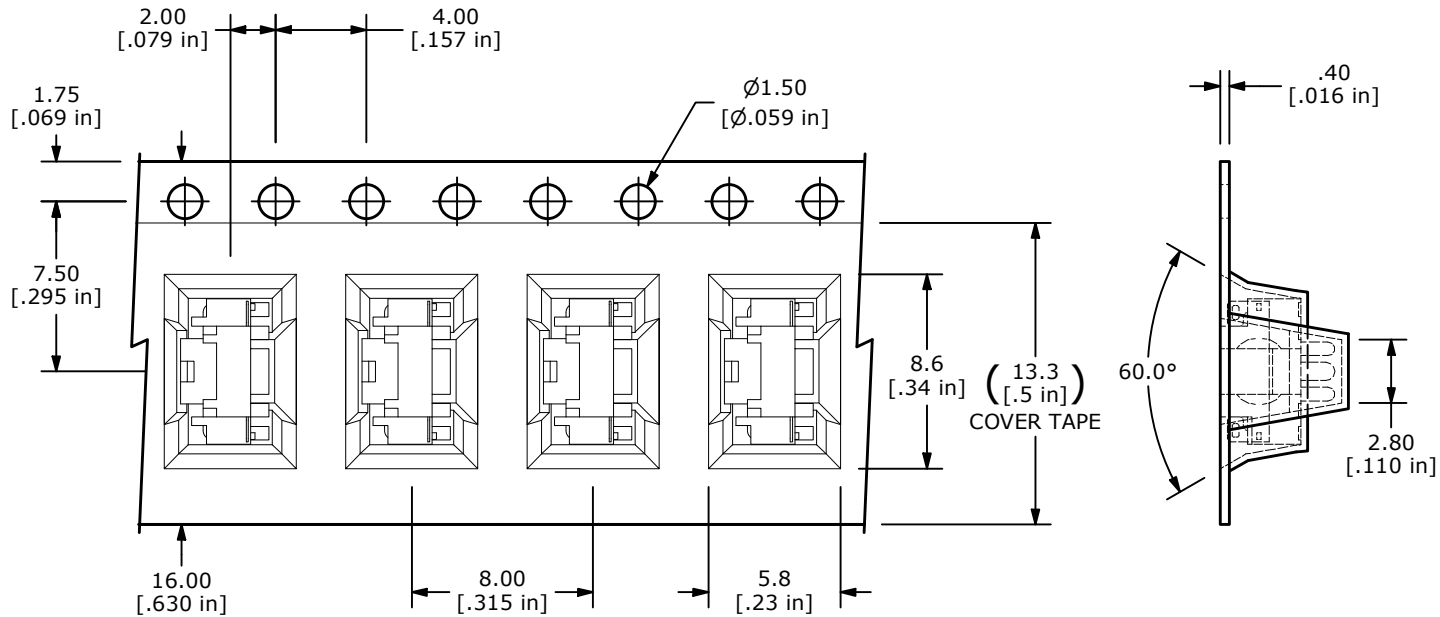
TL3275 SERIES TACT SWITCH

BODY DIMENSIONS



TL3275 SERIES TACT SWITCH

BODY DIMENSIONS TAPE AND REEL



TL3275 SERIES TACT SWITCH

RECOMMENDED SOLDER PROCESS

Most contamination problems can be prevented by exercising care during the cleaning and soldering process. Care should be taken not to immerse or spray unsealed switches during flux removal. Contact E-Switch for specific soldering recommendations and specifications not shown. Generalized soldering procedures are outlined below.

“TYPICAL” SMT REFLOW (Pb and Pb-Free)

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate ($T_{s_{max}}$ to T_p)	3 °C/second max.	3 °C/second max.
Preheat		
-Temperature Min ($T_{s_{min}}$)	100 °C	150 °C
-Temperature Max ($T_{s_{max}}$)	150 °C	200 °C
-Time ($t_{s_{min}}$ to $t_{s_{max}}$)	60-120 seconds	60-180 seconds
Time Maintained above:		
-Temperature (T_L)	183 °C	217 °C
-Time (t_L)	60-150 seconds	60-150 seconds
Time within 5 °C of actual Peak Temperature (t_p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package surface.

